

JK-SMD1210

Model	V_{max}	I_{max}	I_{hold}	I_{trip}	P_d	Maximum time to trip		Resistance	
	(Vdc)	(A)	(A)	(A)	Max. (W)	Current	Time	$R_{i_{min}}$	$R_{1_{max}}$
						(A)	(Sec)	(W)	(W)
SMD1210-005	60	100	0.05	0.15	0.6	0.25	1.50	2.8	50
SMD1210-010	30	100	0.10	0.30	0.6	0.50	0.60	0.8	15
SMD1210-020	30	100	0.20	0.40	0.6	8.0	0.02	0.40	5
SMD1210-035-30V	30	100	0.35	0.75	0.6	8.0	0.20	0.20	1.3
SMD1210-035	16	100	0.35	0.75	0.6	8.0	0.20	0.20	1.3
SMD1210-050	16	100	0.50	1.00	0.6	8.0	0.10	0.18	0.9
SMD1210-075	6	100	0.75	1.50	0.6	8.0	0.10	0.07	0.4
SMD1210-110	6	100	1.10	2.20	0.6	8.0	0.30	0.05	0.21
SMD1210-110-12V	12	100	1.10	2.20	0.8	8.0	0.30	0.05	0.25
SMD1210-150	6	100	1.50	3.00	0.8	8.0	0.50	0.03	0.21
SMD1210-175	6	100	1.75	3.50	0.8	8.0	0.60	0.02	0.08
SMD1210-200	6	100	2.00	4.00	0.8	8.0	1.00	0.015	0.07

I_H =Hold current:maximum current at which the device will not trip at 25°C still air.

I_T =Trip current:minimum current at which the device will always trip at 25°C still air.

V_{max} =Maximum voltage device can withstand without damage at rated current.

I_{max} =Maximum fault current device can withstand without damage at rated voltage.

T_{trip} =Maximum time to trip(s) at assigned current.

P_d =Typical power dissipation:typical amount of power dissipated by the device when in state air environment.

R_{min} =Minimum device resistance at 25°C prior to tripping.

R_{max} =Maximum device resistance at 25°C prior to tripping.